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*IGBT* 

## SGH40N60UFD

### **Ultra-Fast IGBT**

#### **General Description**

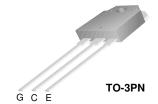
Fairchild's UFD series of Insulated Gate Bipolar Transistors (IGBTs) provides low conduction and switching losses. The UFD series is designed for applications such as motor control and general inverters where high speed switching is a required feature.

#### **Features**

- · High speed switching
- Low saturation voltage :  $V_{CE(sat)} = 2.1 \text{ V } @ I_C = 20 \text{A}$
- · High input impedance
- CO-PAK, IGBT with FRD : t<sub>rr</sub> = 42ns (typ.)

#### **Applications**

AC & DC motor controls, general purpose inverters, robotics, and servo controls.





## Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Description		SGH40N60UFD	Units
V <sub>CES</sub>	Collector-Emitter Voltage		600	V
V <sub>GES</sub>	Gate-Emitter Voltage		± 20	V
_	Collector Current	@ $T_C = 25^{\circ}C$	40	Α
I <sub>C</sub>	Collector Current	@ T <sub>C</sub> = 100°C	20	Α
I <sub>CM (1)</sub>	Pulsed Collector Current		160	Α
I <sub>F</sub>	Diode Continuous Forward Current	@ T <sub>C</sub> = 100°C	15	Α
I <sub>FM</sub>	Diode Maximum Forward Current		160	Α
$P_{D}$	Maximum Power Dissipation	@ T <sub>C</sub> = 25°C	160	W
	Maximum Power Dissipation	@ T <sub>C</sub> = 100°C	64	W
T <sub>J</sub>	Operating Junction Temperature		-55 to +150	°C
T <sub>stg</sub>	Storage Temperature Range		-55 to +150	°C
T <sub>L</sub>	Maximum Lead Temp. for Soldering Purposes, 1/8" from Case for 5 Seconds		300	°C

Notes:
(1) Repetitive rating: Pulse width limited by max. junction temperature

#### **Thermal Characteristics**

Symbol	Parameter	Тур.	Max.	Units
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction-to-Case		0.77	°C/W
$R_{\theta JC}(DIODE)$	Thermal Resistance, Junction-to-Case		1.7	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		40	°C/W

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Cha	racteristics					
BV <sub>CES</sub>	Collector-Emitter Breakdown Voltage	$V_{GE} = 0V, I_{C} = 250uA$	600			٧
$\Delta B_{VCES}/$ $\Delta T_J$	Temperature Coefficient of Breakdown Voltage	$V_{GE} = 0V$ , $I_C = 1mA$		0.6		V/°C
I <sub>CES</sub>	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0V$			250	uA
I <sub>GES</sub>	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$			± 100	nA
On Cha	racteristics					
V <sub>GE(th)</sub>	G-E Threshold Voltage	$I_C = 20$ mA, $V_{CE} = V_{GE}$	3.5	4.5	6.5	V
	Collector to Emitter	$I_C = 20A$ , $V_{GE} = 15V$		2.1	2.6	V
V <sub>CE(sat)</sub>	Saturation Voltage	$I_C = 40A$ , $V_{GE} = 15V$		2.6		V
D :					•	
Dynami C <sub>ies</sub>	c Characteristics Input Capacitance			1430		pF
C <sub>oes</sub>	Output Capacitance	$V_{CE} = 30V_{,} V_{GE} = 0V_{,}$		170		pF
C <sub>res</sub>	Reverse Transfer Capacitance	f = 1MHz		50		pF
t <sub>d(on)</sub>	ng Characteristics Turn-On Delay Time			15		ns
t <sub>r</sub>	Rise Time	1		30		ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{CC} = 300 \text{ V}, I_{C} = 20\text{A},$		65	130	ns
t <sub>f</sub>	Fall Time	$R_G = 10\Omega, V_{GE} = 15V,$		50	150	ns
E <sub>on</sub>	Turn-On Switching Loss	Inductive Load, T <sub>C</sub> = 25°C		160		uJ
E <sub>off</sub>	Turn-Off Switching Loss			200		uJ
				360	600	
	Total Switching Loss					uJ
E <sub>ts</sub>	Total Switching Loss Turn-On Delay Time			30		uJ ns
E <sub>ts</sub>				30 37		
E <sub>ts</sub> t <sub>d(on)</sub> t <sub>r</sub>	Turn-On Delay Time	V <sub>CC</sub> = 300 V, I <sub>C</sub> = 20A,			200	ns
$\begin{array}{c} E_{ts} \\ t_{d(on)} \\ \hline t_r \\ t_{d(off)} \\ t_f \end{array}$	Turn-On Delay Time Rise Time	$V_{CC} = 300 \text{ V, } I_{C} = 20\text{A,}$ $R_{G} = 10\Omega, V_{GE} = 15\text{V,}$		37		ns ns
$\begin{array}{c} E_{ts} \\ t_{d(on)} \\ t_{r} \\ \\ t_{d(off)} \\ t_{f} \end{array}$	Turn-On Delay Time Rise Time Turn-Off Delay Time			37 110	200	ns ns ns
$\begin{array}{c} E_{ts} \\ t_{d(on)} \\ t_{r} \\ t_{d(off)} \\ t_{f} \\ E_{on} \end{array}$	Turn-On Delay Time Rise Time Turn-Off Delay Time Fall Time	$R_G = 10\Omega, V_{GE} = 15V,$		37 110 144	200 250	ns ns ns
E <sub>ts</sub> t <sub>d(on)</sub> t <sub>r</sub> t <sub>d(off)</sub> t <sub>f</sub> E <sub>on</sub> E <sub>off</sub> E <sub>ts</sub>	Turn-On Delay Time Rise Time Turn-Off Delay Time Fall Time Turn-On Switching Loss	$R_G = 10\Omega, V_{GE} = 15V,$		37 110 144 310	200 250 	ns ns ns ns uJ uJ
E <sub>ts</sub> t <sub>d(on)</sub> t <sub>r</sub> t <sub>d(off)</sub> t <sub>f</sub> E <sub>on</sub> E <sub>off</sub> E <sub>ts</sub>	Turn-On Delay Time Rise Time Turn-Off Delay Time Fall Time Turn-On Switching Loss Turn-Off Switching Loss Total Switching Loss Total Gate Charge	$R_G = 10\Omega$ , $V_{GE} = 15V$ , Inductive Load, $T_C = 125^{\circ}C$	  	37 110 144 310 430	200 250 	ns ns ns ns uJ
$\begin{array}{c} E_{ts} \\ \hline t_{d(on)} \\ \hline t_r \\ \hline t_{d(off)} \\ \hline t_f \\ \hline E_{on} \\ \hline E_{off} \\ \hline E_{ts} \\ \hline Q_g \\ \end{array}$	Turn-On Delay Time Rise Time Turn-Off Delay Time Fall Time Turn-On Switching Loss Turn-Off Switching Loss Total Switching Loss	$R_{G} = 10\Omega, V_{GE} = 15V,$ Inductive Load, $T_{C} = 125^{\circ}C$ $V_{CE} = 300 \text{ V}, I_{C} = 20A,$	   	37 110 144 310 430 740	200 250   1200	ns ns ns ns uJ uJ
$\begin{array}{c} E_{ts} \\ \hline E_{ts} \\ \hline t_{d(on)} \\ \hline t_r \\ \hline t_{d(off)} \\ \hline t_f \\ \hline E_{on} \\ \hline E_{off} \\ \hline E_{ts} \\ \hline Q_g \\ \hline Q_{ge} \\ \hline Q_{gc} \\ \end{array}$	Turn-On Delay Time Rise Time Turn-Off Delay Time Fall Time Turn-On Switching Loss Turn-Off Switching Loss Total Switching Loss Total Gate Charge	$R_G = 10\Omega$ , $V_{GE} = 15V$ , Inductive Load, $T_C = 125^{\circ}C$	    	37 110 144 310 430 740 97	200 250   1200 150	ns ns ns ns uJ uJ uJ

## Electrical Characteristics of DIODE $T_{C} = 25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Units
V	Diode Forward Voltage	I <sub>F</sub> = 15A	$T_C = 25^{\circ}C$		1.4	1.7	V
$V_{FM}$			T <sub>C</sub> = 100°C		1.3		
+	Diode Reverse Recovery Time		$T_C = 25^{\circ}C$		42	60	ns
t <sub>rr</sub>	blode neverse necovery fille		T <sub>C</sub> = 100°C		74		
	Diode Peak Reverse Recovery	I <sub>F</sub> = 15A,	$T_C = 25^{\circ}C$		4.5	6.0	۸
Irr	Current	di/dt = 200A/us	T <sub>C</sub> = 100°C		6.5		Α
	Diode Reverse Recovery Charge		$T_C = 25^{\circ}C$		80	180	nC
$Q_{rr}$			T <sub>C</sub> = 100°C		220		

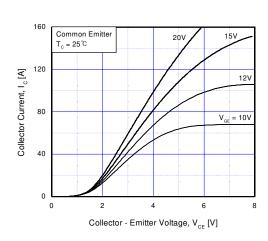


Fig 1. Typical Output Characteristics

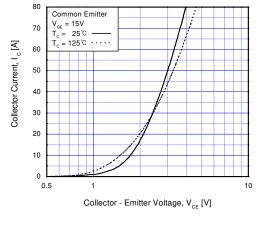


Fig 2. Typical Saturation Voltage Characteristics

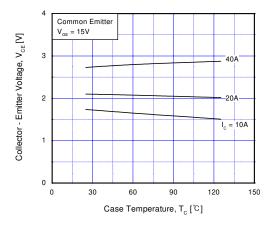


Fig 3. Saturation Voltage vs. Case
Temperature at Variant Current Level

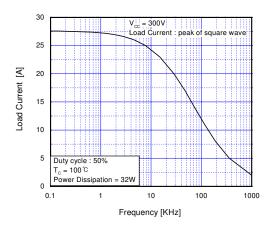


Fig 4. Load Current vs. Frequency

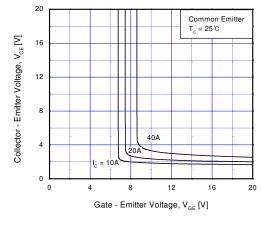


Fig 5. Saturation Voltage vs. V<sub>GE</sub>

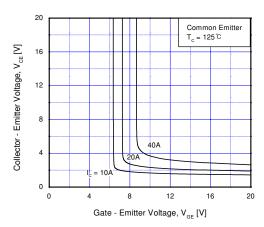
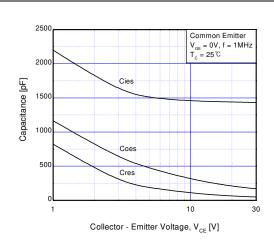


Fig 6. Saturation Voltage vs.  $V_{\rm GE}$ 

SGH40N60UFD Rev. A1

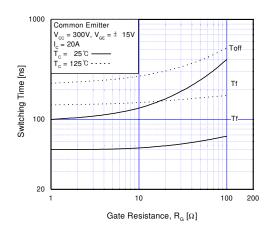
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Gate Resistance,  $R_{\rm G}$  [ $\Omega$ ]

Fig 7. Capacitance Characteristics

Fig 8. Turn-On Characteristics vs.
Gate Resistance



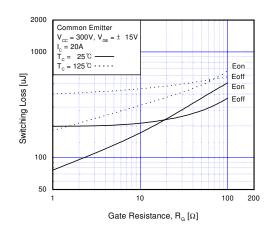
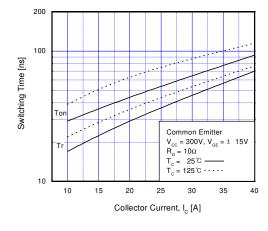


Fig 9. Turn-Off Characteristics vs.
Gate Resistance

Fig 10. Switching Loss vs. Gate Resistance



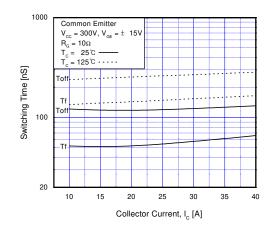
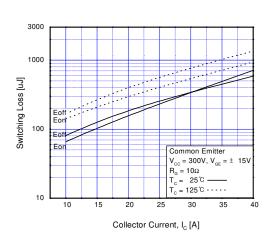


Fig 11. Turn-On Characteristics vs. Collector Current

Fig 12. Turn-Off Characteristics vs. Collector Current



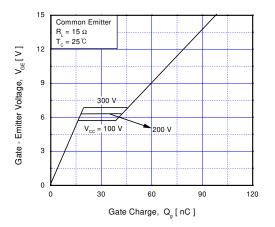
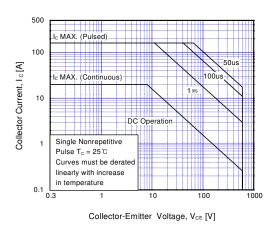


Fig 13. Switching Loss vs. Collector Current

Fig 14. Gate Charge Characteristics



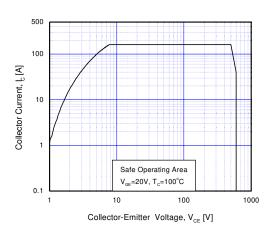


Fig 15. SOA Characteristics

Fig 16. Turn-Off SOA Characteristics

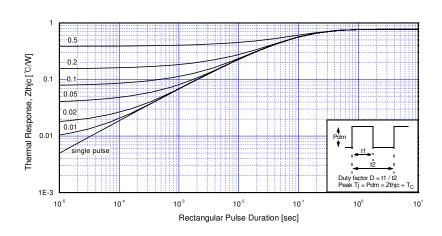
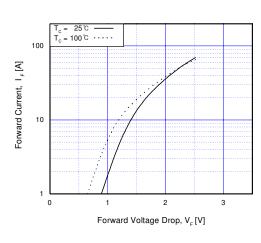


Fig 17. Transient Thermal Impedance of IGBT



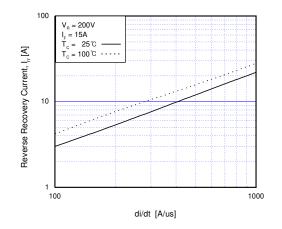
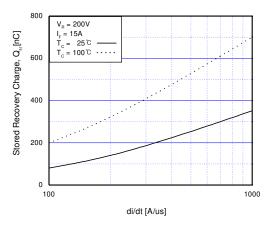


Fig 18. Forward Characteristics

Fig 19. Reverse Recovery Current



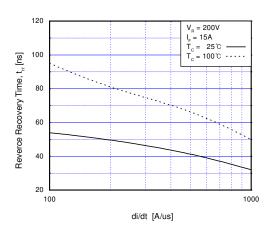
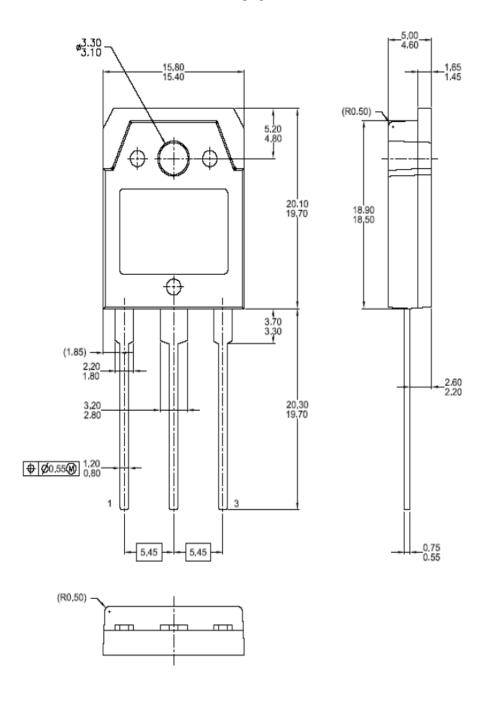


Fig 20. Stored Charge

Fig 21. Reverse Recovery Time



TO-3PN



Dimensions in Millimeters

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